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(54) Title: ATOMIC LAYER DEPOSITION SEAM REDUCTION

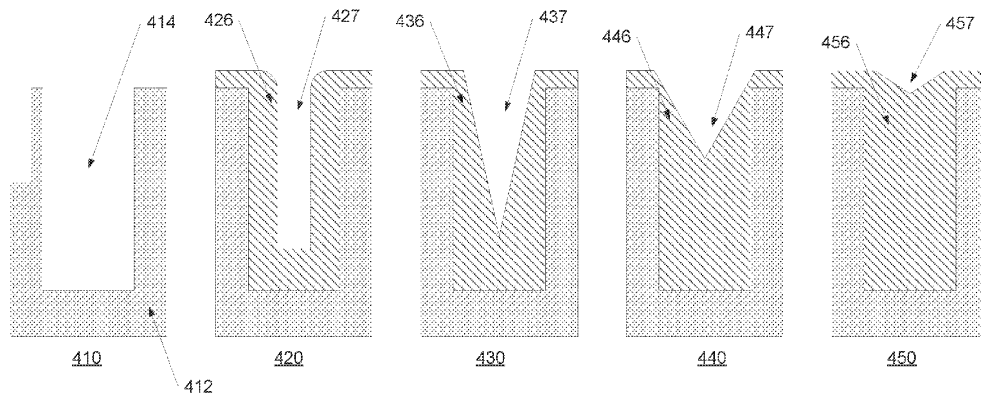


FIG. 4

(57) Abstract: Methods and apparatuses for depositing material into features are described herein. Methods involve depositing an oxide material and then sputtering the oxide material to reduce seams. The oxide material may be deposited by an ALD process.

[Continued on next page]



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